L. Number	Hits	Search Text	DB	Time stamp
1	2	("6639188").PN.	USPAT; US-PGPUB;	2004/08/09 11:11
			EPO; JPO; DERWENT;	
2	2	("20030136776").PN.	IBM_TDB USPAT;	2004/08/09
		( 2000 200 7 7 7 7 2 2 7 7 2 7 2 7 2 7 7 2	US-PGPUB; EPO; JPO;	11:21
			DERWENT; IBM TDB	
3	6319	ceramic near heater	USPAT; US-PGPUB;	2004/08/09 11:21
			EPO; JPO; DERWENT;	1 + 1 - 2 1
	104000	temperature near control or thermistor	IBM_TDB USPAT;	2004/08/09
4	194808	temperature near control of thermistor	US-PGPUB; EPO; JPO;	11:21
			DERWENT; IBM TDB	
5	2182	corner near chamfered	USPAT; US-PGPUB;	2004/08/09 11:22
			EPO; JPO;	11:22
			DERWENT; IBM_TDB	2004/00/00
6	1237112	through near hole or aperture	USPAT; US-PGPUB;	2004/08/09 11:23
			EPO; JPO; DERWENT;	
7	1159517	groove	IBM_TDB USPAT;	2004/08/09
			US-PGPUB; EPO; JPO;	11:23
			DERWENT; IBM_TDB	2004/00/00
8	38839	ceramic adj substrate	USPAT; US-PGPUB;	2004/08/09 11:23
			EPO; JPO; DERWENT;	
9	2011	nitride and carbide near ceramic	IBM_TDB USPAT;	2004/08/09 11:24
			US-PGPUB; EPO; JPO;	11:24
			DERWENT; IBM_TDB	2004/00/00
10	26480	C near surface	USPAT; US-PGPUB;	2004/08/09 11:24
			EPO; JPO; DERWENT;	
11	5277	R near surface	IBM_TDB USPAT;	2004/08/09
			US-PGPUB; EPO; JPO;	11:24
	1015		DERWENT; IBM_TDB	2004/08/09
12	121279	diameter near mm	USPAT; US-PGPUB;	11:25
			EPO; JPO; DERWENT;	
13	69565	thickness near mm	IBM_TDB USPAT;	2004/08/09
			US-PGPUB; EPO; JPO;	11:25
	110077	210 (2	DERWENT; IBM_TDB	2004/08/00
14	118375	219/\$.ccls.	USPAT; US-PGPUB;	2004/08/09 11:25
			EPO; JPO; DERWENT;	
	1		IBM_TDB	<u> </u>

			TICDAM	2004/00/00
15	1107	(ceramic near heater ) and (temperature	USPAT;	2004/08/09
		near control or thermistor)	US-PGPUB;	11:25
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
17	9	(ceramic near heater ) and (corner near	USPAT;	2004/08/09
		chamfered)	US-PGPUB;	11:26
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
18	803	(corner near chamfered) and (through near	USPĀT;	2004/08/09
		hole or aperture)	US-PGPUB;	11:26
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
20	3	(nitride and carbide near ceramic) and	USPAT;	2004/08/09
		((ceramic adj substrate) and ((corner	US-PGPUB;	11:26
		near chamfered) and (through near hole or	EPO; JPO;	
		aperture)))	DERWENT;	
		_ *	IBM TDB	
21	73	(ceramic near heater ) and (C near	USPĀT;	2004/08/09
	'3	surface)	US-PGPUB;	11:26
		Sallaco,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
23	5	((ceramic near heater ) and (C near	USPAT;	2004/08/09
123		surface)) and ((ceramic near heater ) and	US-PGPUB;	11:27
1		(R near surface))	EPO; JPO;	
		(K Hear Surrace))	DERWENT;	
			IBM TDB	
22	11	(ceramic near heater ) and (R near	USPAT;	2004/08/09
44		surface)	US-PGPUB;	11:27
		Sullace;	EPO; JPO;	
			DERWENT;	
			IBM TDB	
1.0	5	(corner near chamfered) and ((ceramic	USPAT;	2004/08/09
16	5	near heater ) and (temperature near	US-PGPUB;	11:28
		control or thermistor))	EPO; JPO;	
		CONTEROR OF CHERMITSCOL)	DERWENT;	
	1		IBM TDB	
10	1	(remain add substrate) and ((some man	USPAT;	2004/08/09
19	15	(ceramic adj substrate) and ((corner near	US-PGPUB;	11:33
		chamfered) and (through near hole or	EPO; JPO;	11.00
		aperture))	DERWENT;	
		//#5017406#\\	IBM_TDB	2004/08/09
24	18	(("5817406") or ("2007111") or	USPAT;	2004/08/09
		("5635093") or ("6133557") or ("5643483")	US-PGPUB;	11:39
		or ("6080970")).PN.	EPO; JPO;	1
	ł		DERWENT;	
1			IBM TDB	